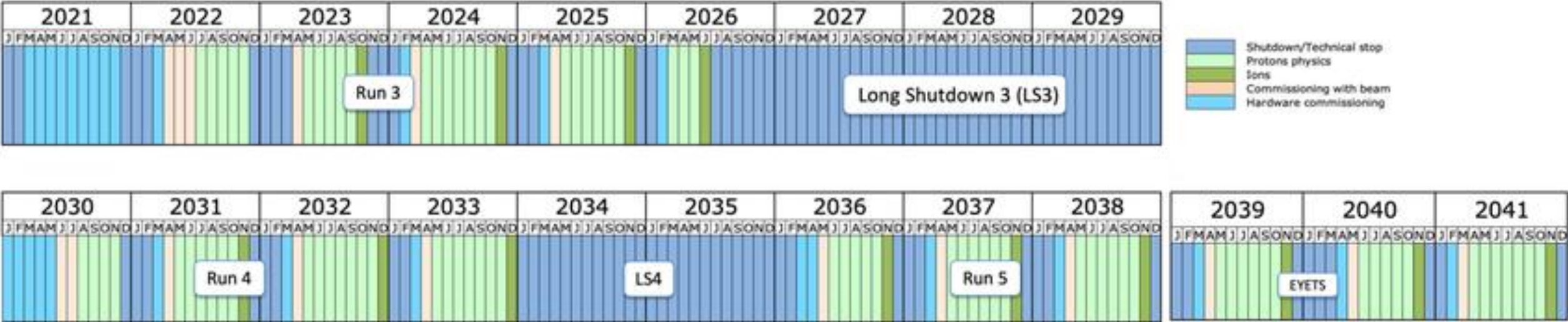

ATLAS HGTD

Bojan Hiti
for HGTD F9 (Gregor, Bojan, Jernej, Iskra, Marko P., Brigita, Ajda)

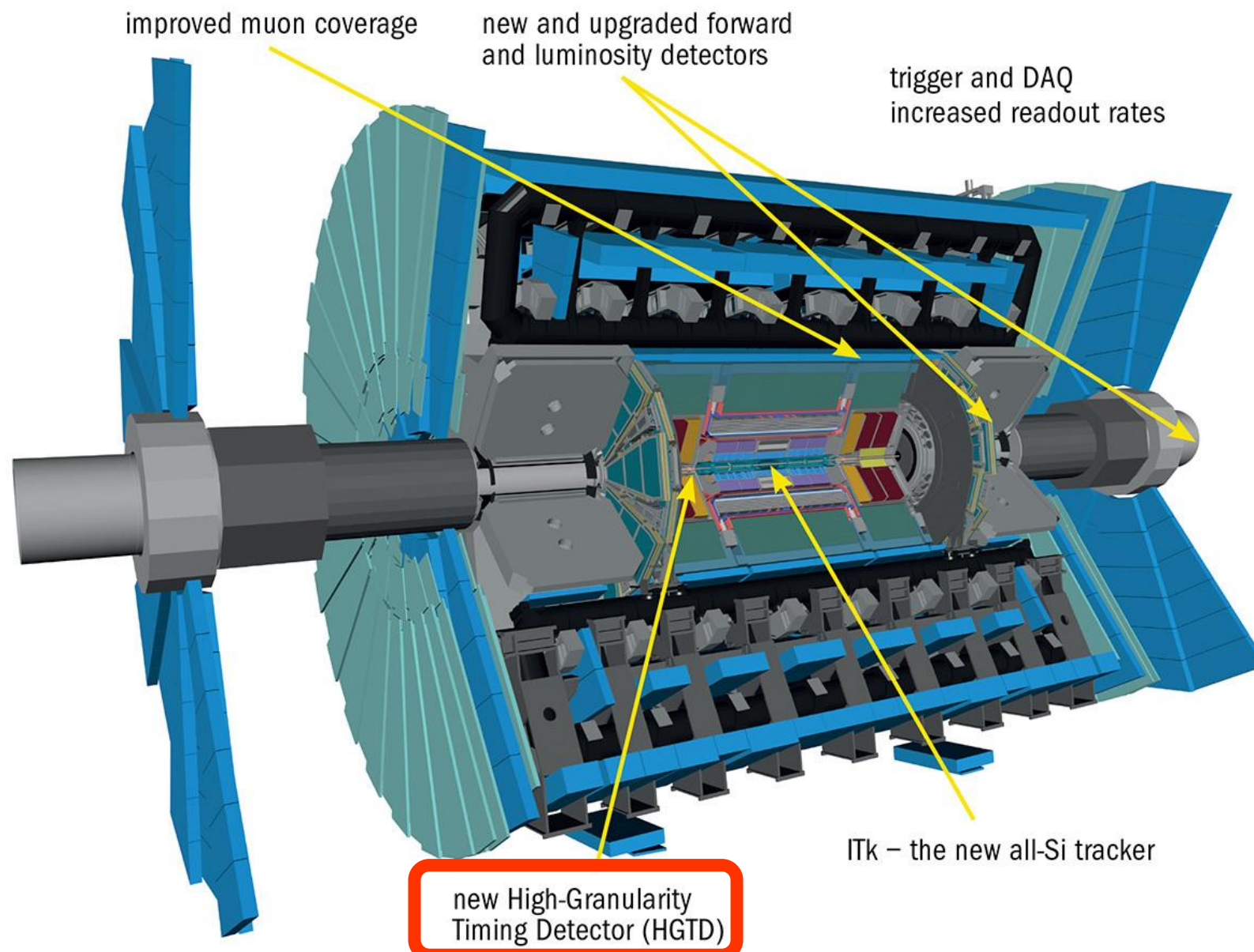
F9 Strategic meeting, Krvavec, 28 September 2026

Long Shutdown 3 (2026-29) : High Luminosity LHC upgrade

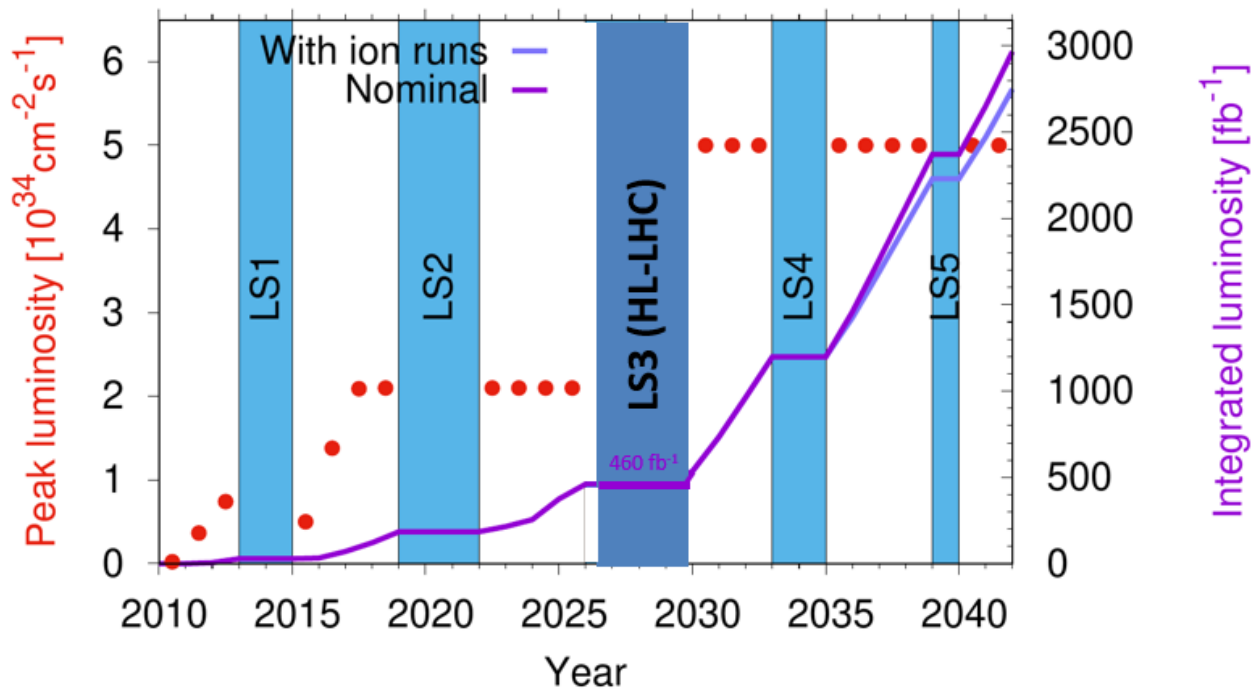


Long Shutdown 4 (2034-36) Opportunity for detector replacements

ATLAS phase 2 upgrade



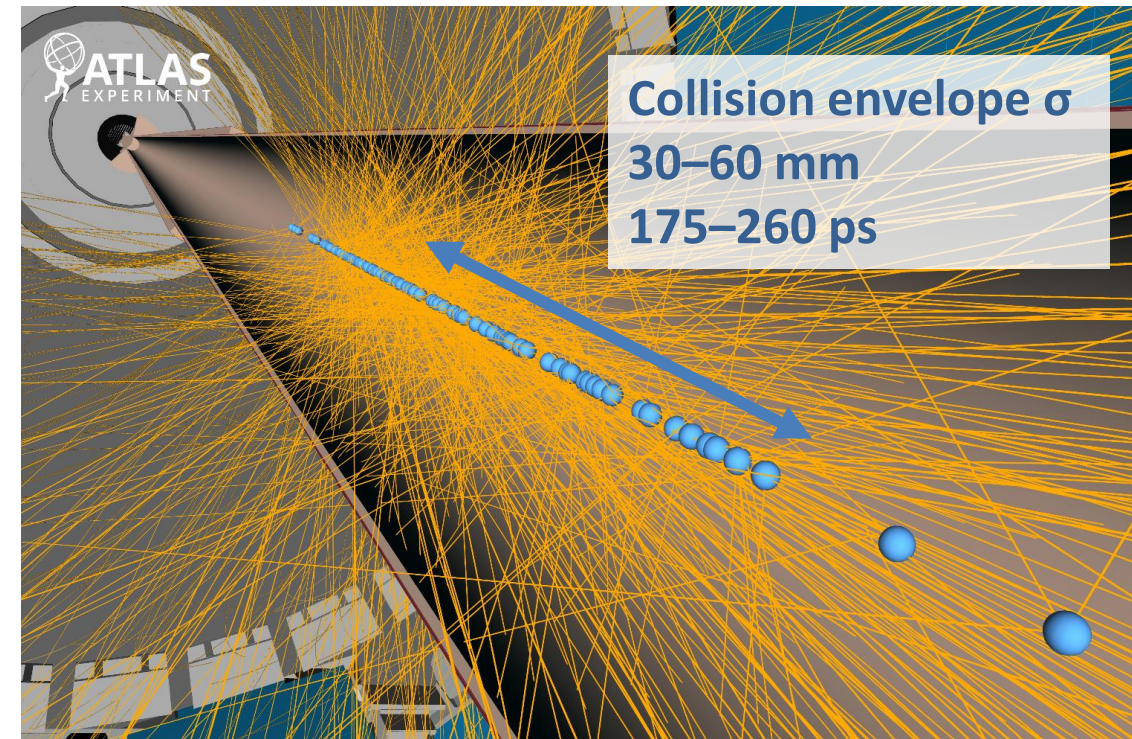
HL-LHC collision environment



$\mathcal{L}_{\text{inst}} = 5 \times 10^{34} \text{ cm}^2/\text{s}$ at HL-LHC

3000 fb^{-1} total in High Lumi phase

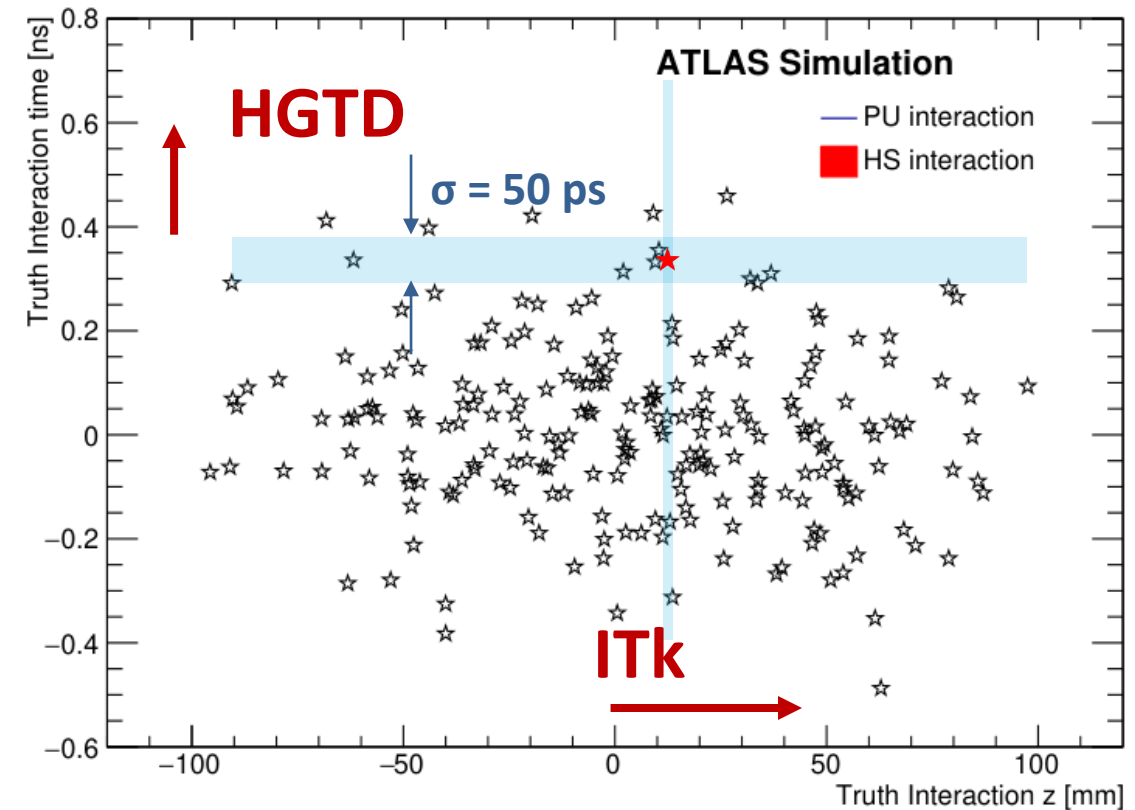
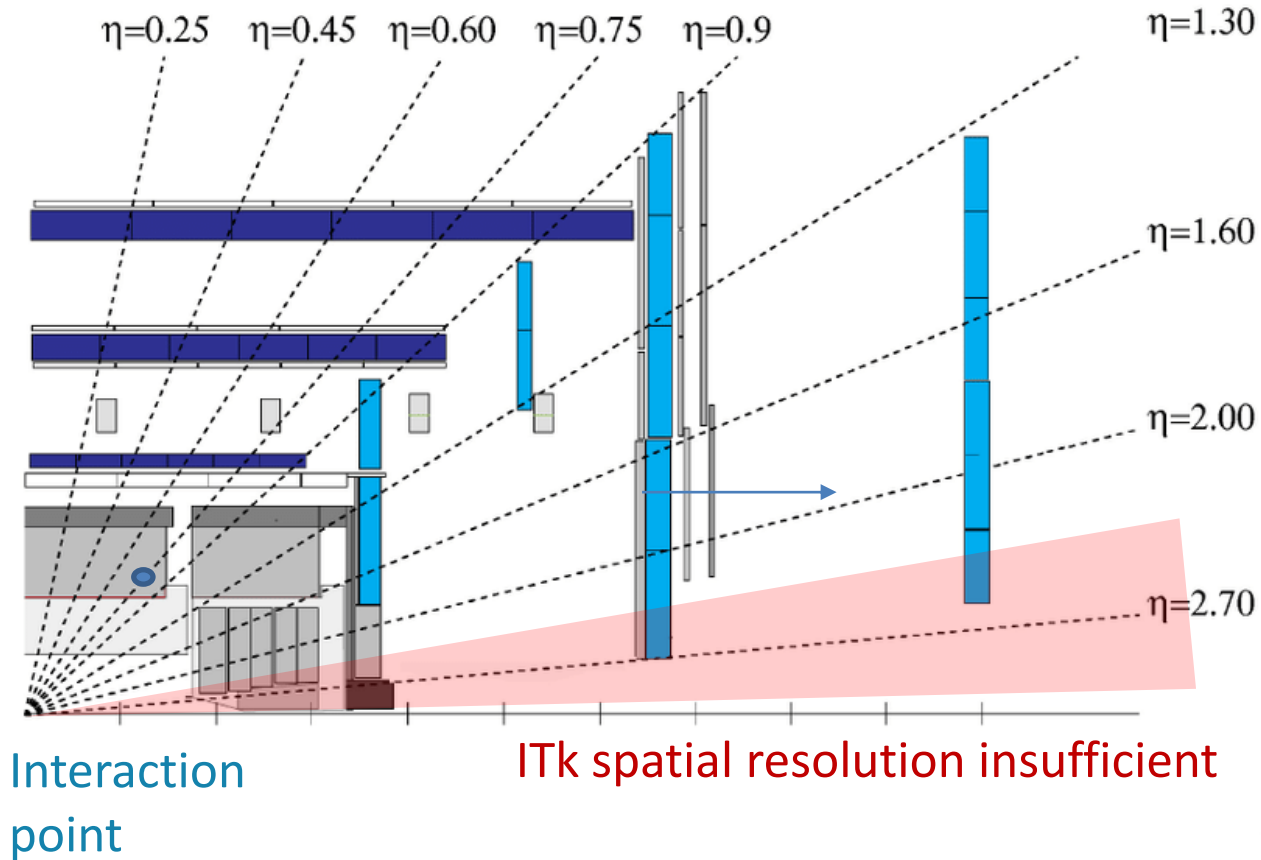
(2010–2026: 460 fb^{-1} , peak $2.3 \times 10^{34} \text{ cm}^2/\text{s}$)



Pile-up value of 200 in experiments

Extreme vertex density & radiation damage

Why High Granularity *Timing* Detector?



HGTD will complement ATLAS Inner Tracker (ITk) with track time measurement (50 ps resolution)
Improved matching of tracks to vertices (bonus: luminosity measurement)

ATLAS HGTD

Two disks between calorimeter
barrels and endcap

Active area
 $12\text{ cm} < r < 64\text{ cm}$

4 sensor layers in each disk
Total thickness 75 mm

Rapidity coverage

$2.4 < |\eta| < 4.0$

z position

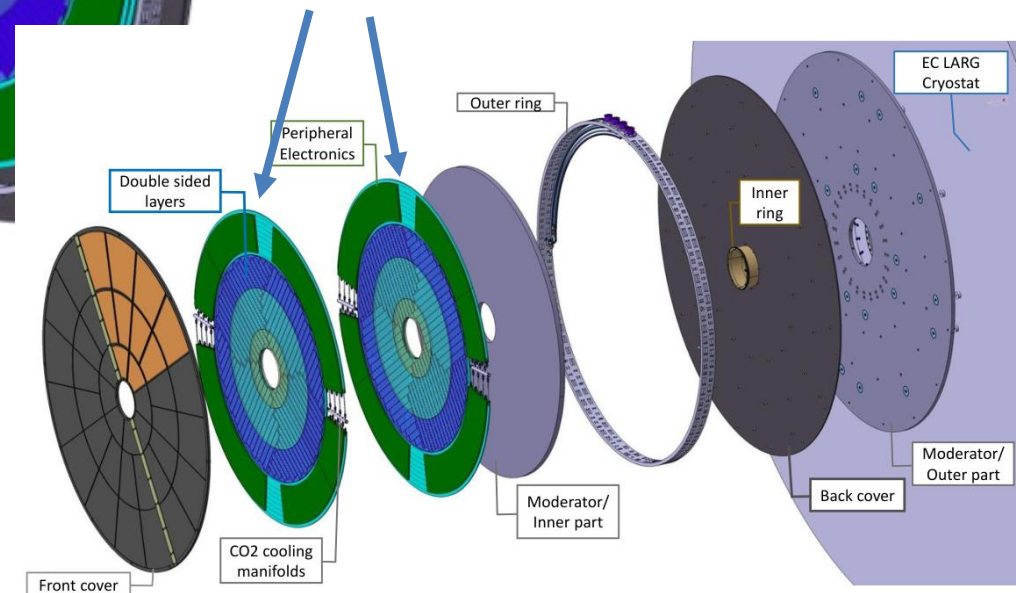
$\pm 3.5\text{ m}$

No. of readout channels

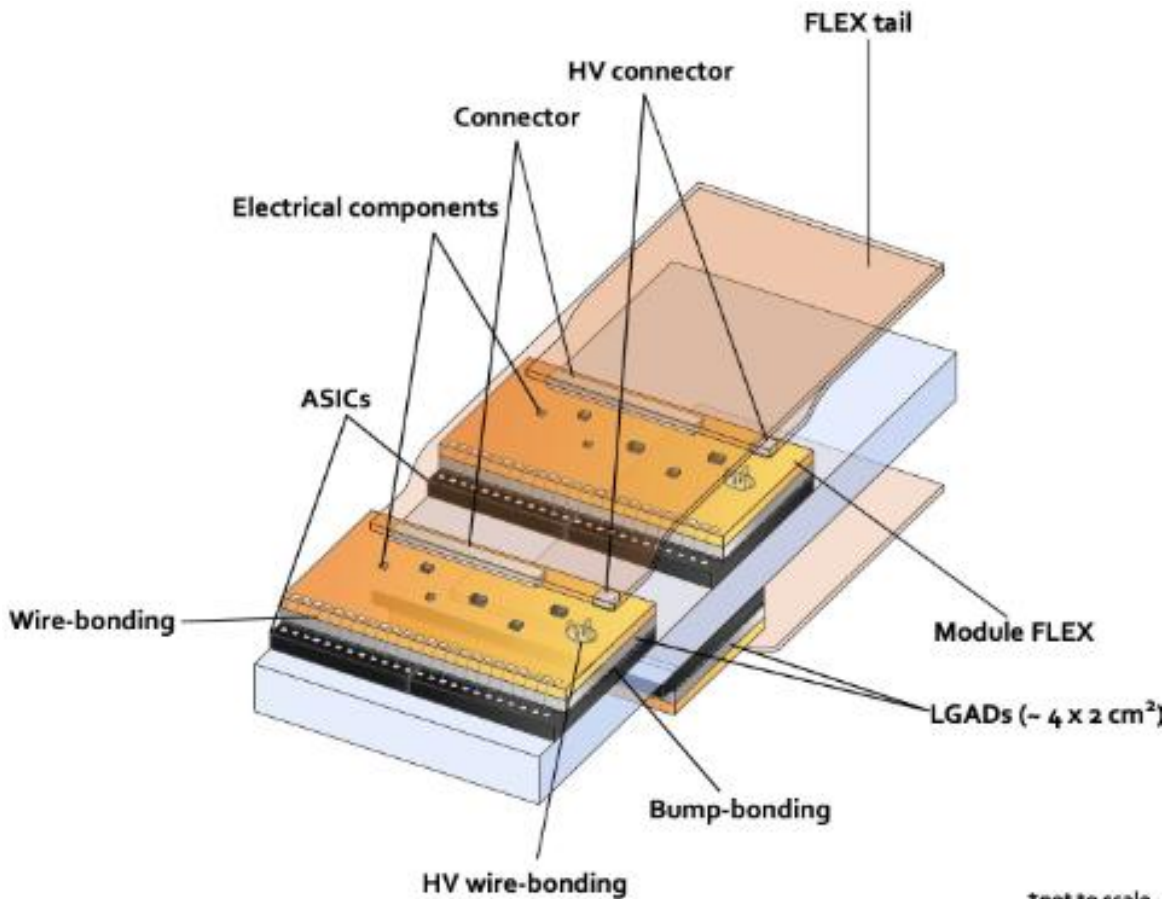
3.6 M

Working temperature

$-30\text{ }^{\circ}\text{C}$ (CO_2)

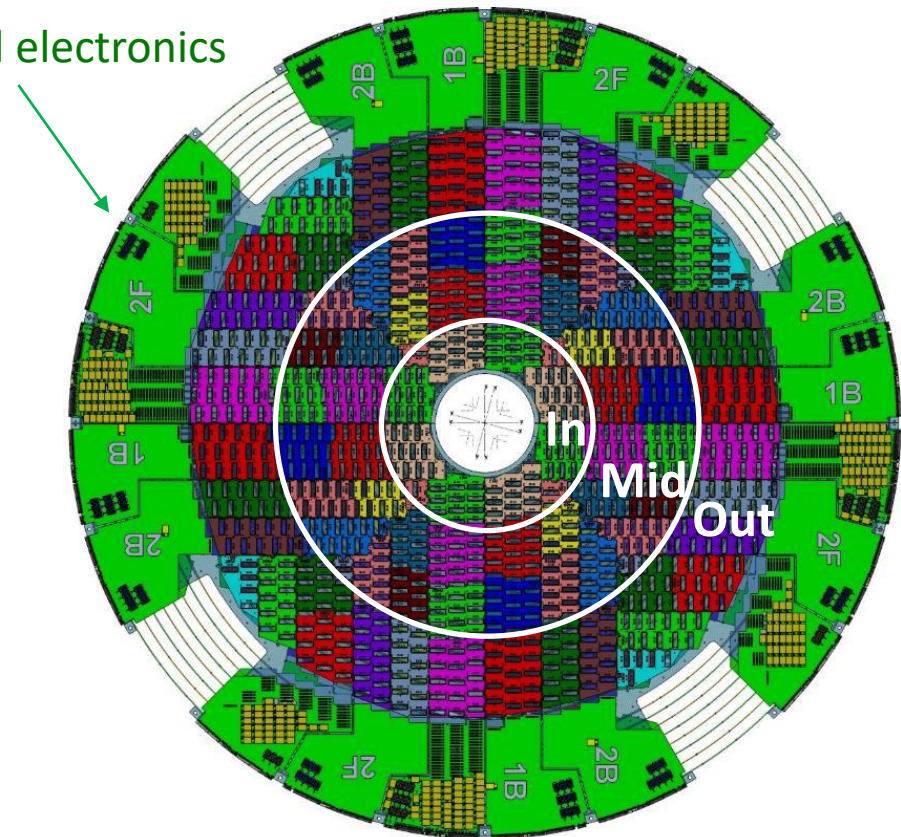


HGTD components



Module: 2 hybrids (sensor + ASIC) + flex circuit
8032 modules in total

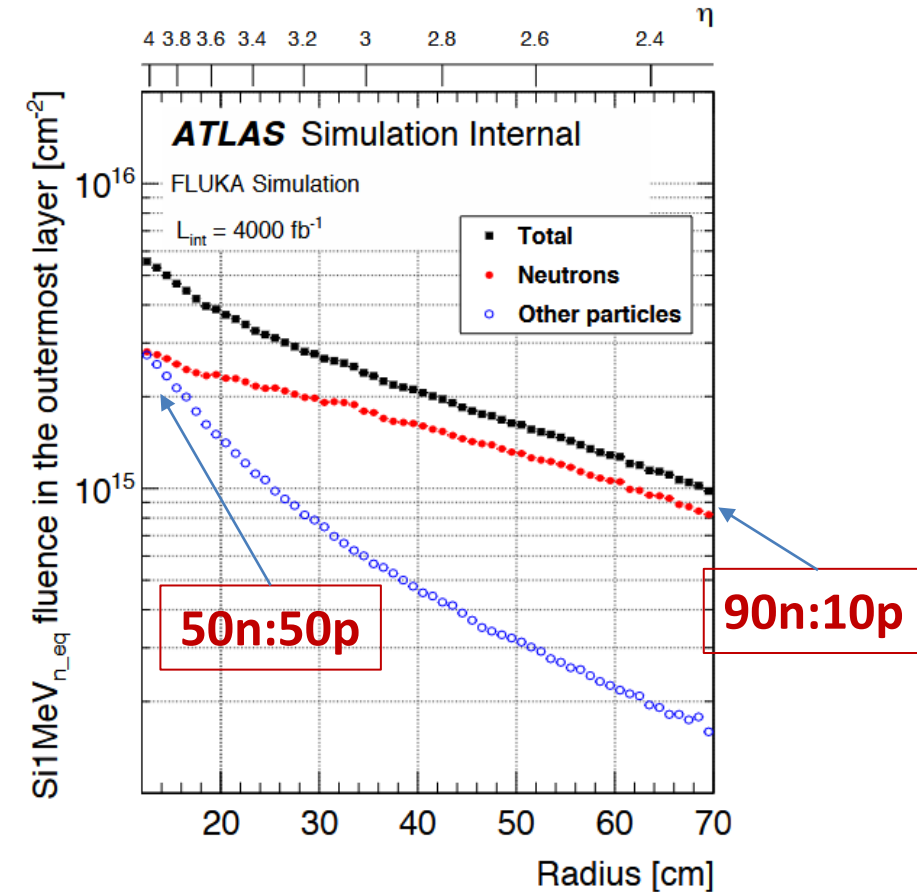
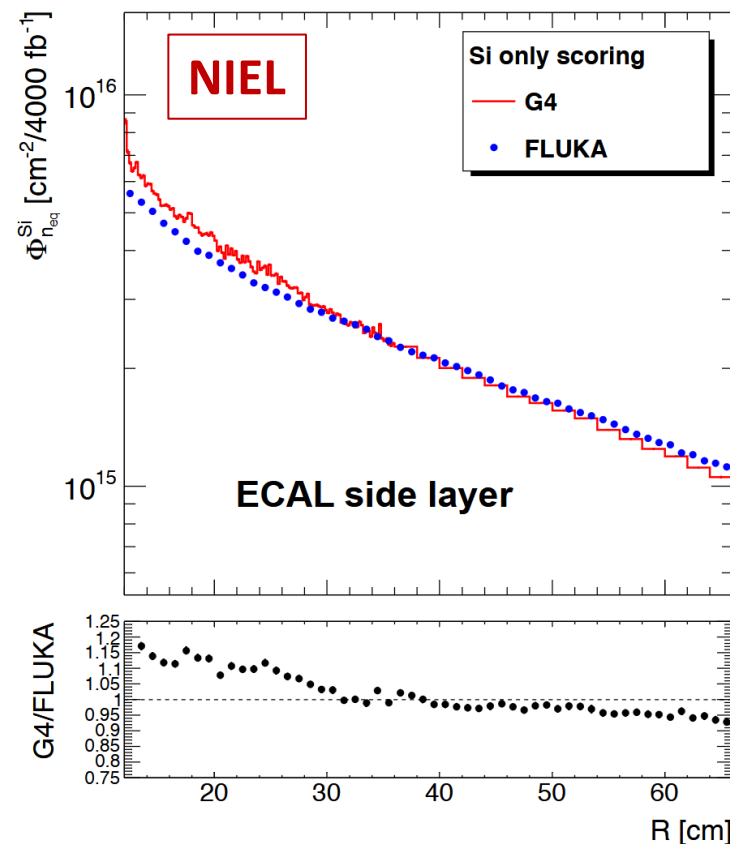
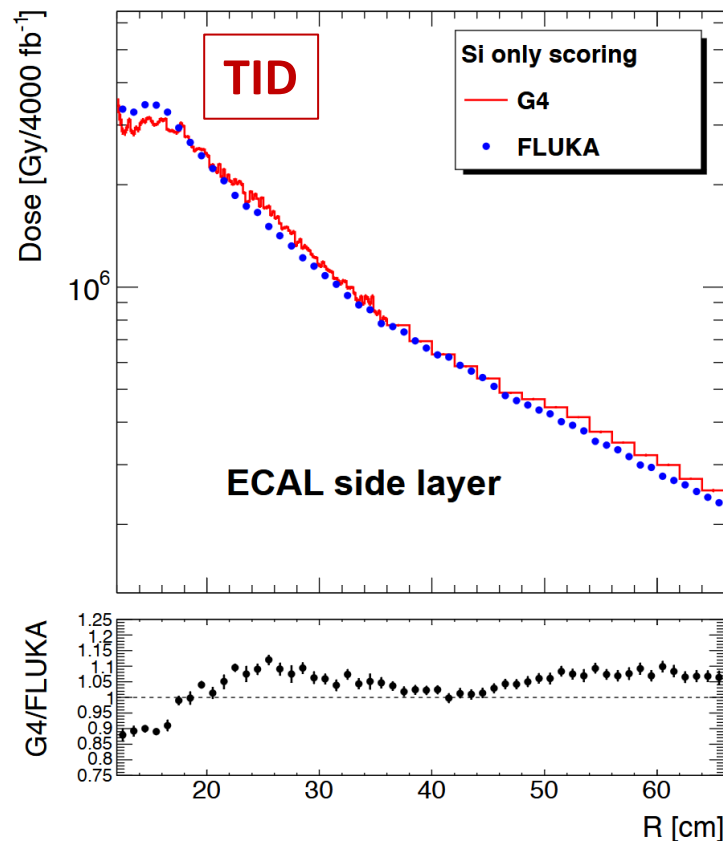
Peripheral electronics



Modules arranged in Detector Units
3 independently replaceable regions (LS4)

HGTD radiation environment

- Simulation of TID, NIEL damage and particle composition in HGTD (for 4000 fb^{-1})
- HGTD is designed for $2.5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$, 2 MGy

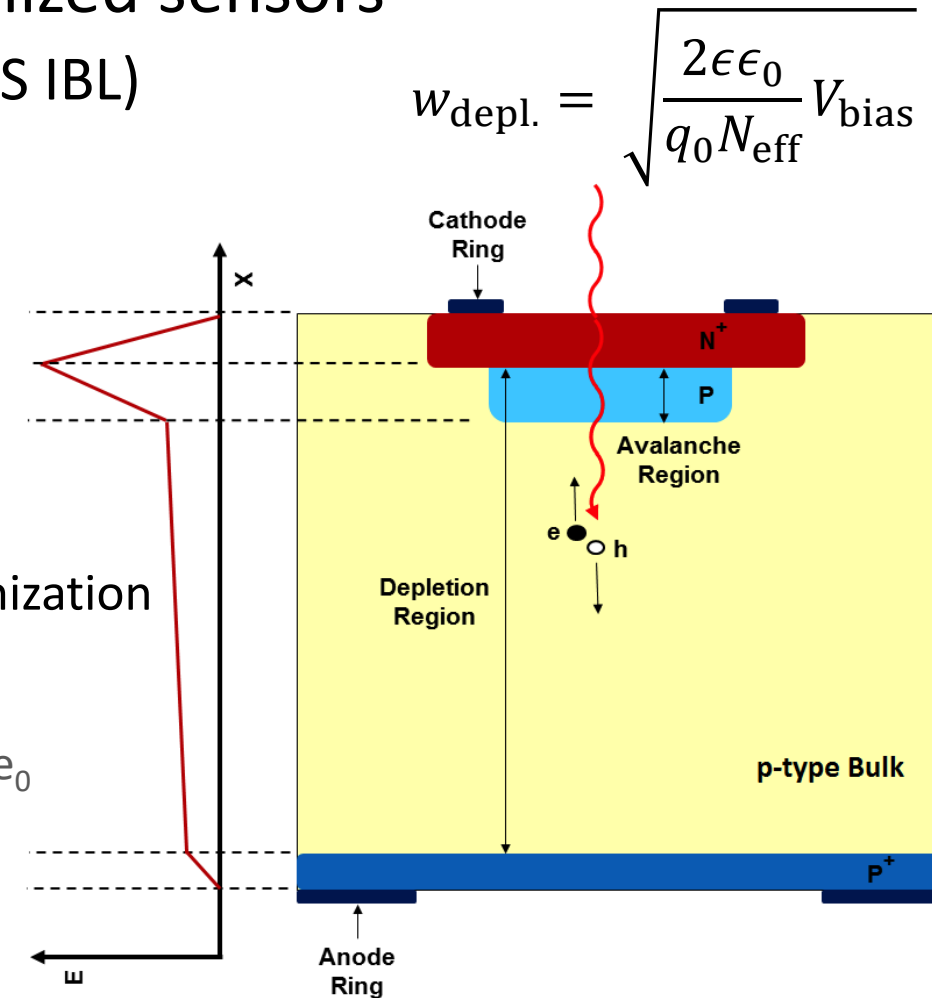


[M. Huhtinen, CERN]

- F9 group activities in HGTD:
- **Sensor group**
 - G. Kramberger is a convener
 - Heavily involved in testing & production quality control (QC)
 - Irradiation test QC performed exclusively at JSI
 - Additional radiation hardness studies – see [Iskra](#)'s talk on Wed
- **Hybrid and module testing**
 - Emerged as leading site for tests after irradiation (see [Marko P.](#)'s talk on Wed)
 - Extending our skillset to ASIC readout
- **Flex tail procurement**
 - Minor contribution of procuring 8.5 % of flex cables

- Time resolution on 50 ps level requires specialized sensors
 - Radiation hard ($2.5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ in HGTD $\approx$ as ATLAS IBL)
 - Fast rise time
 - High signal-to-noise
- Low Gain Avalanche Diode (**LGAD**)
 - Planar n^{++} - p^+ -p silicon sensor with internal gain
 - Highly doped p^+ **gain layer**
 - High electric field $\rightarrow$ charge multiplication by impact ionization
 - Typically 1 μm thick, 25 V to deplete (V_{gl})
 - Gain factor 10–30
 - HGTD sensors 50 μm thick
 - Required charge 4 fC (but 10 fC would be nice)

$$1 \text{ fC} = 6250 e_0$$

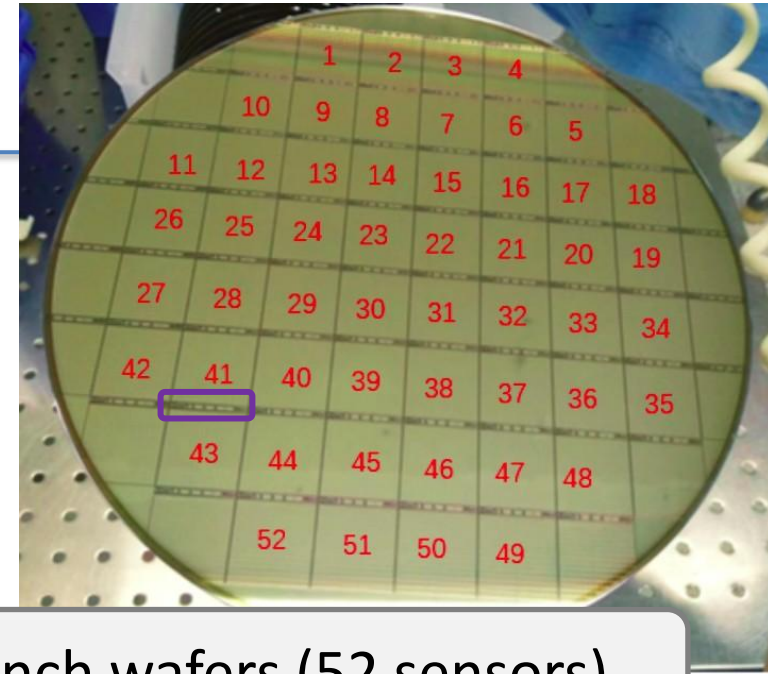


HGTD production sensors

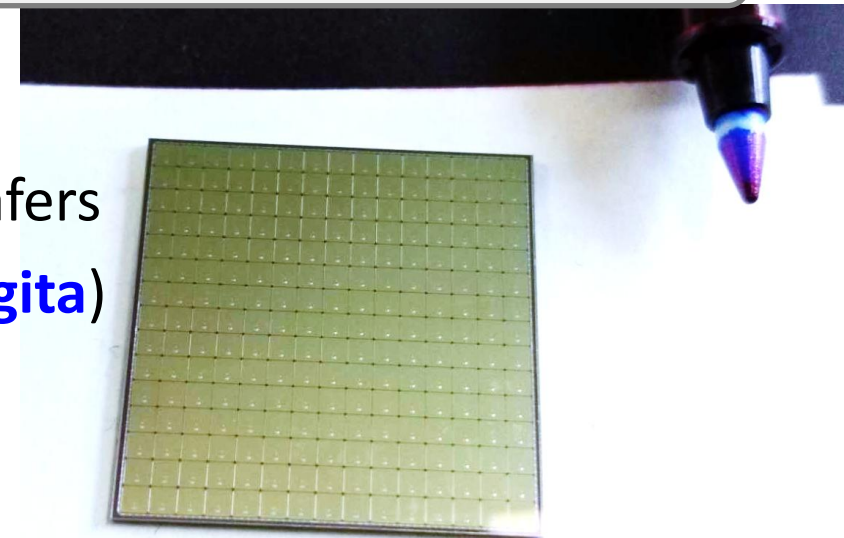
- HGTD sensors produced by IMECAS (China)

Number of pads	15 × 15
Pad size	1.3 mm × 1.3 mm
Effective fill factor	> 85 %
Total size	2 cm × 2 cm
Active/physical thickness	50 μm / 775 μm

- Sensor production is ongoing until mid 2027
 - > 20,000 main sensors required for production ~ 1000 wafers
 - Samples from each wafer irradiated and tested at JSI (**Brigita**)
- Readout ASIC: ALTIROC A (bump bonded)
 - ToA + ToT, 20 ps bin TDC



8-inch wafers (52 sensors)

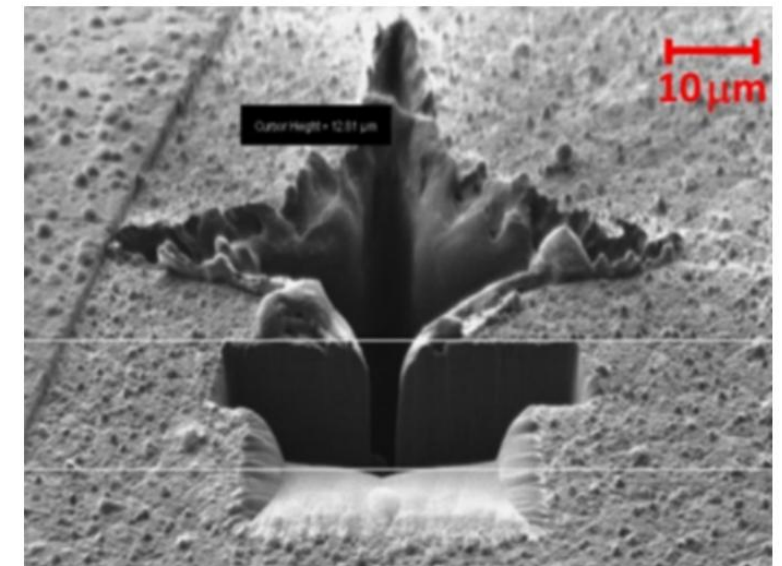


- Neutron and charged hadron radiation damages LGAD sensors
- **Acceptor removal** in gain layer $\rightarrow$ loss of gain $\rightarrow$ performance degradation
- Mitigation by increasing operating bias voltage
 - 100 V before irradiation
 - 550 V after irradiation (11 V/ μ m) is a hard limit due to destructive **Single Event Breakdown (SEB)**
 - SEB investigated by **Alissa Howard** (PhD thesis defended today)

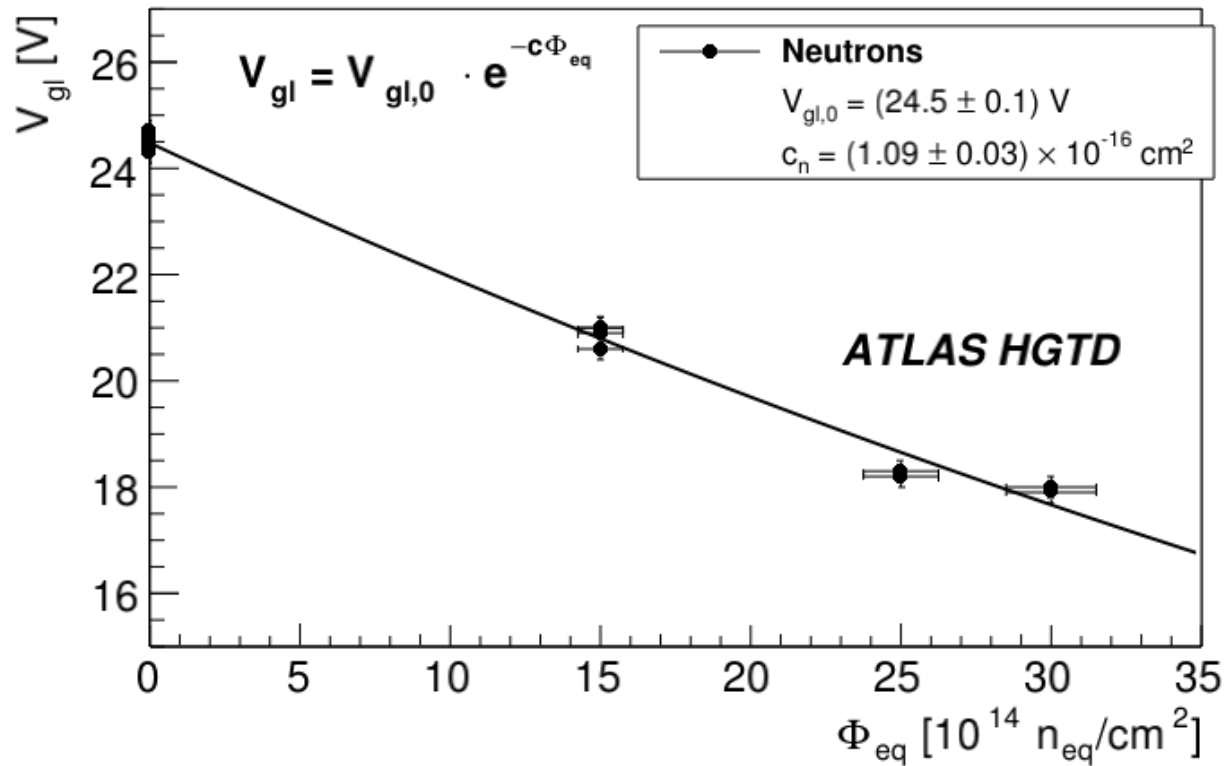
Hot Topic:

Why do we not observe electrical discharge over a 100 μ m gap between sensor (550 V) and ASIC (0 V)?

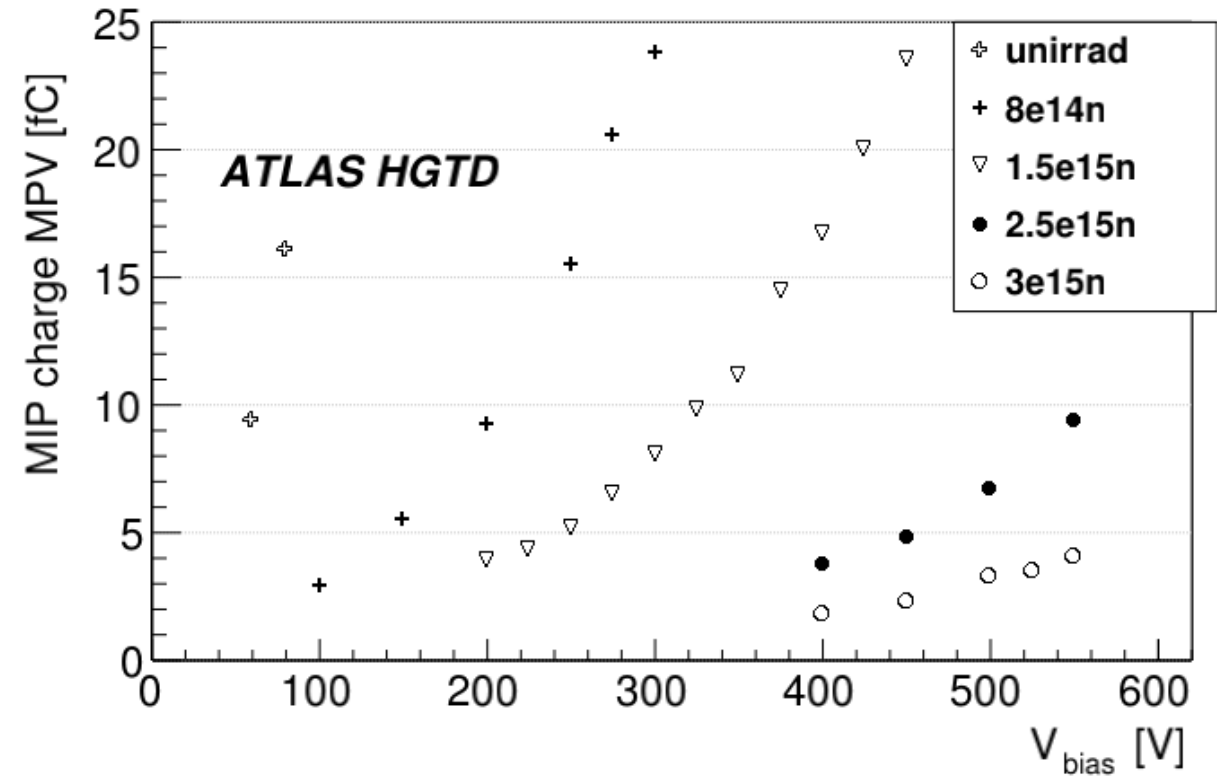
- $V_{gl} = V_{gl,0} \times e^{-c\phi_{eq}}$
 - **c** is called acceptor removal parameter
 - c depends on particle type and energy (LHC mix!)
 - Investigated by **Iskra**
 - Test methods: electrical, laser, radioactive ^{90}Sr



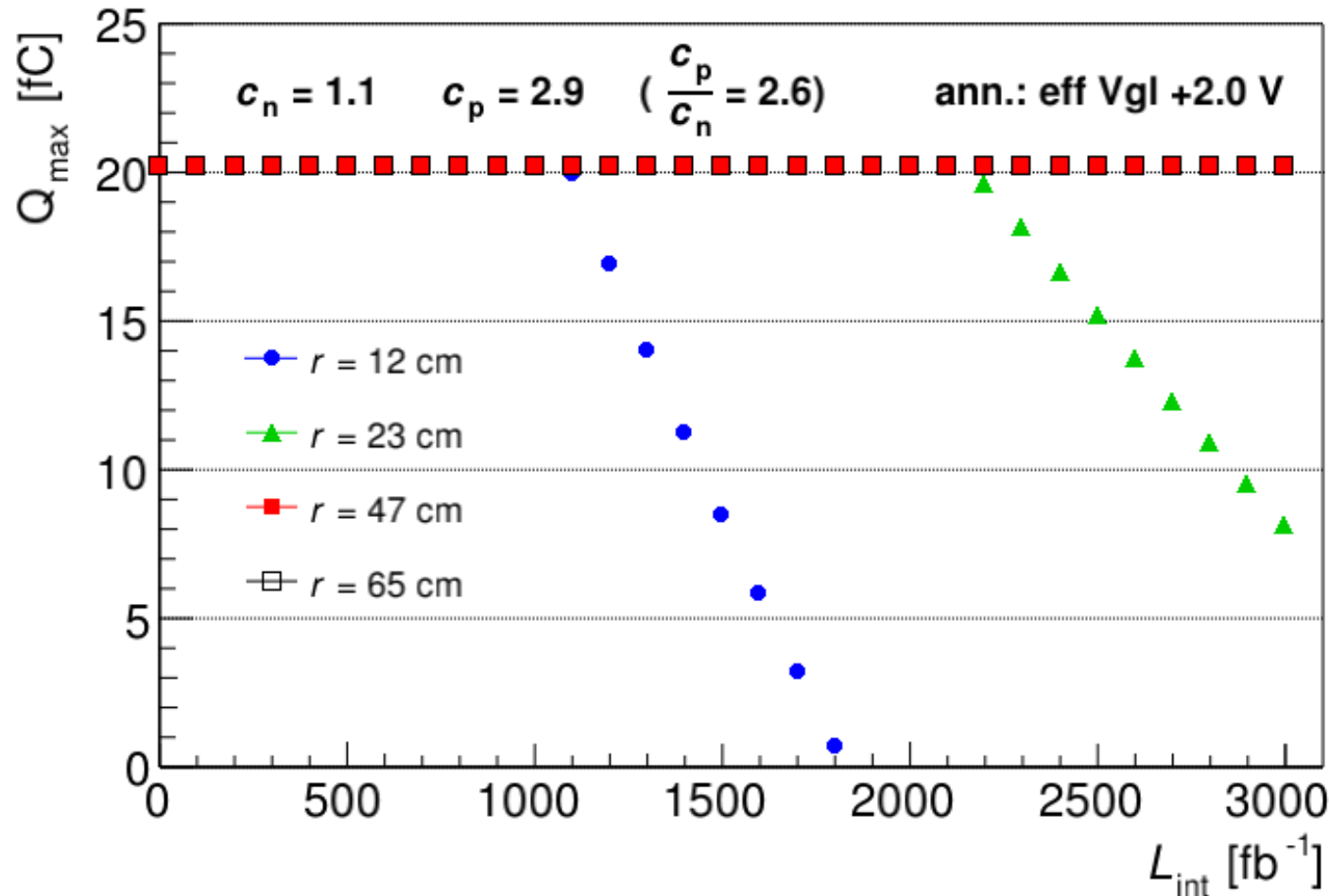
HGTD irradiated sensor performance



Protons are more damaging – see Iskra's talk



Higher voltage is required at higher fluences to collect a fixed charge



- Simulation of collected charge at HL-LHC
- Degradation at small radius quite fast
- Positive effects of long term annealing will be studied by [Ajda](#)

- **Production:** Sensors 50 % done, (finished in 2027)
- **System assembly:** at CERN 2027–2029
- **Performance studies:** will continue at JSI (see Iskra, Marko P. talks)
- **Integration into ATLAS software tools**